

C0603X629C2TACAUTO7411

SMD Auto X8G HT150C Flex, Ceramic, 6.2 pF, +/-0.25 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade, 0603, 0.4 mm



General Information	
Series	SMD Auto X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade
Features	High Temperature, Ultra-Stable, Automotive Grade
RoHS	Yes
Termination	Flexible Termination
Marking	No
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

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S	0.4mm MIN
В	0.45mm +/-0.15mm
Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape

15000

Packaging Quantity

Specifications	
Capacitance	6.2 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.25 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitut	te - and
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